

C1
C2
B1
Cont.

a plurality of substantially flat electrical connectors formed about a perimeter of said die attach pad; and
an encapsulant surrounding a portion of said electrical connectors and a portion of said die attach pad,
wherein said bottom surface of said die attach pad is substantially free of encapsulant.

sub
C2

5. The microelectronic device package according to claim 1, further comprising a plurality of wires coupled to one of said connectors.

B2

6. An electronic device package configured to facilitate electrical connection between a device and a substrate, said package comprising:
a plurality of rows of electrical connectors formed by etching a sheet of conductive material; and
an encapsulant attached to a portion of each of said plurality of electrical connectors, wherein said encapsulant is molded to each said portion by exposing said electrical connectors and a removable material attached to said connectors to a mold process.

REMARKS

Applicants believes that the claims, as amended above, overcome the 35 U.S.C § 102 rejections set forth in the Office Action dates March 27, 2001. Accordingly, reconsideration and allowance of all pending claims 1-9 is earnestly requested.

35 U.S.C. § 102 Rejection

Claims 1-9 stand rejected under 35 U.S.C. §102 as being anticipated by United States Patent No. 5,134,773, issued to LeMaire et al. on August 4, 1992 (hereinafter "LeMaire et al."). Applicants traverses this rejection.

LeMaire et al. discloses an electronic module, including portions of a pre-cut and pre-formed metal strip, solder, wires, a die, and an encapsulant.

Claim 1 is not anticipated or rendered obvious in view of LeMaire et al. because LeMaire et al. does not teach or suggest "a plurality of substantially flat electrical connectors formed

about a perimeter of said die attach pad." Fig. 7 of LeMaire et al. discloses only a single row of connectors about a perimeter of a die and thus does not anticipate claim 1 or claims 2-5 that depend therefrom. Accordingly, Applicants request that the Examiner reconsider and withdraw his rejection to claims 1-5.

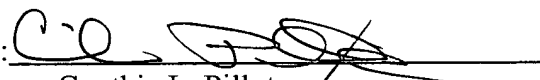
Claim 5 is additionally allowable over the cited reference because LeMaire et al. does not teach or suggest "a plurality of wires coupled to one of said connectors." Accordingly, Applicants submit that claim 5 is independently allowable over the cited reference.

Claim 6 is not anticipated or rendered obvious in view of LeMaire et al. because LeMaire et al. does not teach or suggest "a plurality of rows of electrical connectors formed by etching a sheet of conductive material." Rather, LeMaire et al. only discloses a single row of connectors formed using "cut" metal. Accordingly, Applicants submit that claim 6 and claims 7-9 that depend therefrom are patentable over the cited reference.

Conclusion

In view of the foregoing remarks, Applicants believe that the pending claims are allowable over the cited references and Applicants therefore earnestly request allowance of all pending claims. The undersigned would welcome a telephone call at the telephone number listed below if such would advance prosecution of this application.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

1. A microelectronic device package comprising:
[a substantially flat electrical connector formed from a metal frame;]
a die attach pad [electrically isolated from said connector], said pad having a
bottom surface; [and]
a plurality of substantially flat electrical connectors formed about a perimeter of
said die attach pad; and
an encapsulant surrounding a portion of said electrical [connector] connectors and
a portion of said die attach pad,
wherein said bottom surface of said die attach pad is substantially free of
encapsulant.

5. The microelectronic device package according to claim 1, further comprising a
plurality of wires coupled to one of said [plurality of rows of] connectors [located about a
perimeter of said pad].

6. An electronic device package configured to facilitate electrical connection
between a device and a substrate, said package comprising:
a plurality of rows of electrical connectors formed by etching a sheet of conductive
material; and
an encapsulant attached to a portion of each of said plurality of electrical connectors,
wherein said encapsulant is molded to each said portion by exposing said electrical
connectors and a removable material attached to said connectors to a mold process.